



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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2SC3611

Silicon NPN epitaxial planar type

For video amplifier

■ Features

- High transition frequency f_T
- Small collector output capacitance (Common base, input open circuited) C_{ob}
- Wide current range
- TO-126B package which requires no insulation plate for installation to the heat sink

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

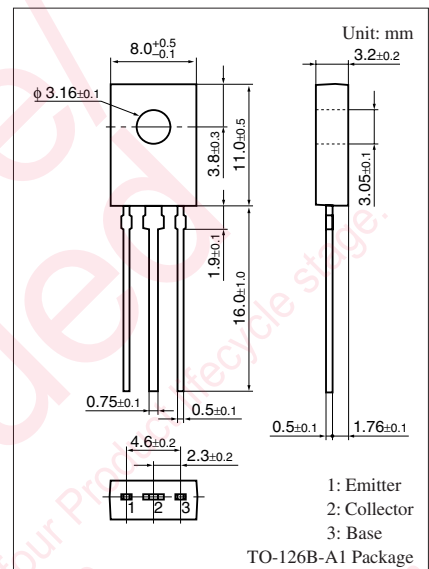
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	110	V
Collector-emitter voltage (Resistor between B and E)	V_{CER}	100	V
Collector-emitter voltage (Base open)	V_{CEO}	50	V
Emitter-base voltage (Collector open)	V_{EBO}	3.5	V
Collector current	I_C	150	mA
Peak collector current	I_{CP}	300	mA
Collector power dissipation	P_C	1.2 4.0 *	W
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

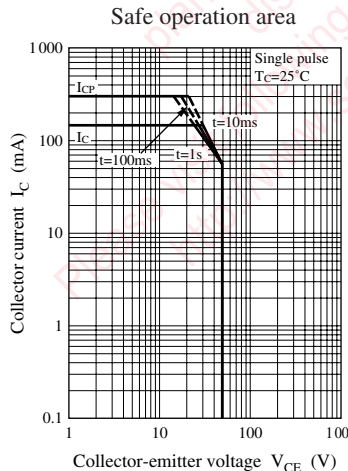
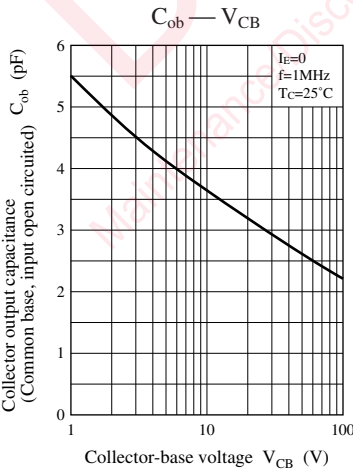
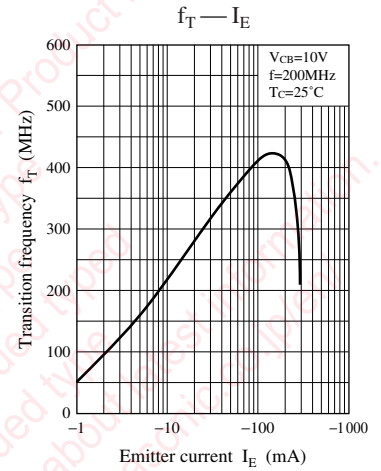
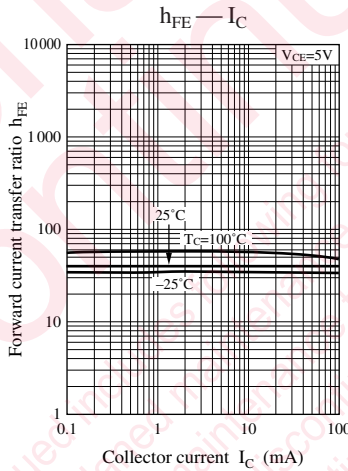
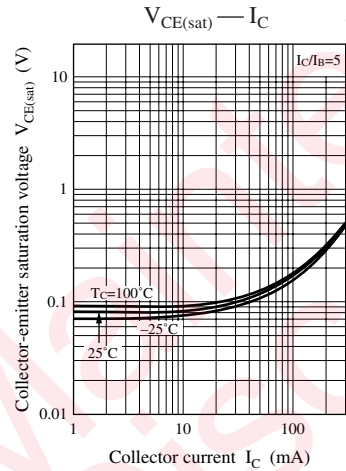
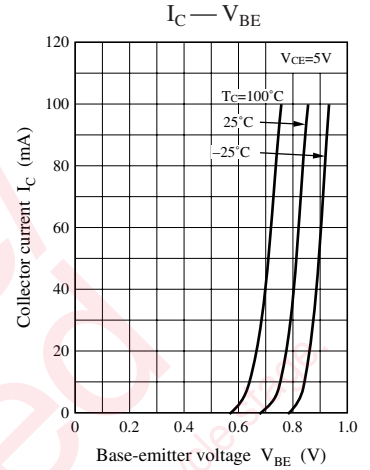
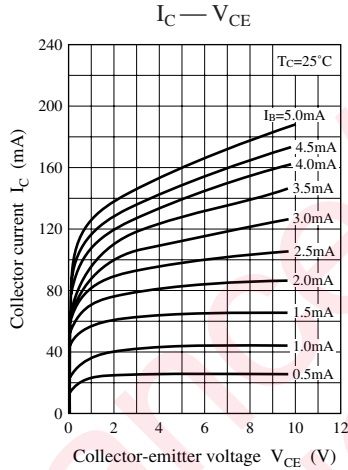
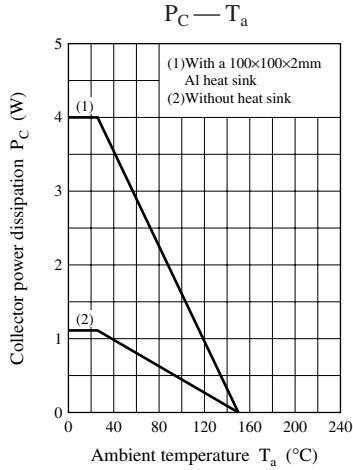
Note) *: With a $100 \times 100 \times 2$ mm Al heat sink

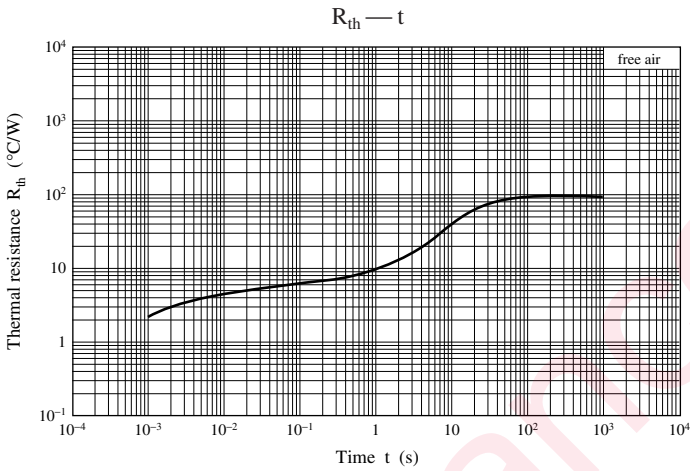
■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_C = 100 \mu\text{A}$, $I_E = 0$	110			V
Collector-emitter voltage (Resistor between B and E)	V_{CER}	$I_C = 500 \mu\text{A}$, $R_{BE} = 470 \Omega$	100			V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 1 \text{ mA}$, $I_B = 0$	50			V
Emitter-base voltage (Collector open)	V_{EBO}	$I_E = 100 \mu\text{A}$, $I_C = 0$	3.5			V
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 35 \text{ V}$, $I_B = 0$			10	μA
Forward current transfer ratio	h_{FE}	$V_{CE} = 5 \text{ V}$, $I_C = 100 \text{ mA}$	20			—
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = 150 \text{ mA}$, $I_B = 15 \text{ mA}$			0.5	V
Transition frequency	f_{T1}	$V_{CB} = 10 \text{ V}$, $I_E = -10 \text{ mA}$, $f = 200 \text{ MHz}$		300		MHz
	f_{T2}	$V_{CB} = 10 \text{ V}$, $I_E = -110 \text{ mA}$, $f = 200 \text{ MHz}$		350		
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = 30 \text{ V}$, $I_E = 0$, $f = 1 \text{ MHz}$		3		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.







Maintenance/Discontinued includes following four Product lifecycle stage.
Discontinued
planned maintenance type
maintenance type
planned discontinued type
discontinued type
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